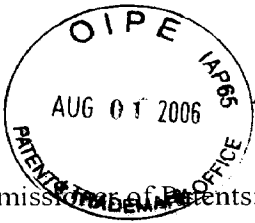


DS

8-1-06



08-04-2006



103286315

ASSIGNMENT

EET

Commissioner of Patents:

Please record the attached document.

1. Name of conveying party:
- a) Jaime Bayan
 - b) Nghia Thuc Tu
 - c) Lim Fong
 - d) Chan Peng Yeen
2. Name and address of receiving party:
- a) Name: National Semiconductor Corporation
 - Address: 2900 Semiconductor Drive
Santa Clara, CA 95051
3. Nature of conveyance:
- | | | | |
|-------------------------------------|--------------------|--------------------------|-------------------|
| <input checked="" type="checkbox"/> | Assignment | <input type="checkbox"/> | Merger |
| <input type="checkbox"/> | Security Agreement | <input type="checkbox"/> | Change of Name |
| <input type="checkbox"/> | Other _____ | <input type="checkbox"/> | License Agreement |

Execution Dates: a) Jaime Bayan, May 23, 2006, b) Nghia Thuc Tu, May 24, 2006, c) Lim Fong, July 3, 2006 and d) Chan Peng Yeen, June 1, 2006

4. Application Number or Patent Number: 11/372,481

The title of the application is:

DIE ATTACH METHOD AND LEADFRAME STRUCTURE

5. Please send all correspondence concerning this document to:

Beyer Weaver & Thomas, LLP
P.O. Box 70250
Oakland, CA 94612-0250
Customer Number: 022434

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 3.41): \$40.00

- ☒ Enclosed.
- ☐ Charge to Deposit Account No. 500388 (Order No. _____).
- ☒ Any additional fees are authorized to be charged to Deposit Account No. 500388 (Order No. NSC1P349).

Date: July 26, 2006

Steve D Beyer
Registration No. 31,234

Total number of pages including this cover sheet, attachments and documents: 05

08/03/2006 NJRHA1 00000060 11372481 40.00 OP
01 FC:8021

Attorney Docket No. NSC1P349/P06556

(Revised 9/03)

ASSIGNMENT OF PATENT APPLICATION

Whereas I, an undersigned inventor, have invented certain new and useful improvements as set forth in the patent application entitled:

DIE ATTACH METHOD AND LEADFRAME STRUCTURE

(Atty. Docket No. NSC1P349/P06556), (check one)

- ☐ for which I have executed a U.S. patent application on even date herewith. (Accompanying)
☒ which bears U.S. application No. 11/372,481 . (Not accompanying)
☐ which is a U.S. provisional application. (Accompanying)

For good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, I, an undersigned inventor, hereby:

- 1) Sell, assign and transfer to National Semiconductor Corporation, a Delaware corporation having a place of business at 2900 Semiconductor Drive, Santa Clara, CA 95051 ("ASSIGNEE"), the entire right, title and interest in any and all improvements and inventions disclosed in, applications based upon, and patents granted upon (including foreign patents and the right to claim priority), the above-referenced application.
- 2) Authorize and request the Commissioner of Patents to issue any and all United States Patents resulting from said application or any division, continuation, substitute, renewal, re-examination or reissue thereof to the ASSIGNEE.
- 3) Agree to execute all papers and documents and, entirely at the ASSIGNEE's expense, perform any acts which are reasonably necessary in connection with the prosecution of said application, as well as any derivative applications thereof, foreign applications based thereon, and/or the enforcement of patents resulting from such applications.
- 4) Agree that the terms, covenants and conditions of this assignment shall inure to the benefit of the ASSIGNEE, its successors, assigns and other legal representatives, and shall be binding upon the inventor, as well as the inventor's heirs, legal representatives and assigns.
- 5) Warrant and represent that I have not entered and will not enter into any assignment, contract, or understanding that conflicts with this assignment.
- 6) Authorize and request my attorney/agent to insert above the application No. in order to assist with recordal of this assignment.

Signed on the date indicated beside my signature.

1. Inventor Signature:

Jaime Bayan

Date:

5/23/06

State of California

County of

Santa Clara

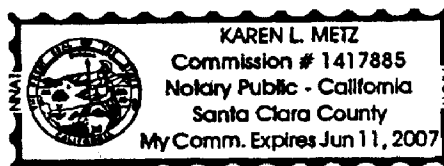
SS.

On this 23rd day of May, in the year 2006, before me, Karen L. Metz, Notary Public, personally appeared Jaime Bayan, personally known to me (or proved to me on the basis of satisfactory evidence) to be the person whose name is subscribed to the within instrument, and acknowledged to me that ~~he~~she executed the same in ~~his~~her authorized capacity(ies), and that by ~~his~~her signature on the instrument the person, or the entity upon behalf of which the person acted, executed the instrument.

WITNESS my hand and official seal.

Notary Signature

Karen L. Metz



2. Inventor Signature:

Nghia Thuc Tu

Date:

5/24/06

State of California

County of

Santa Clara

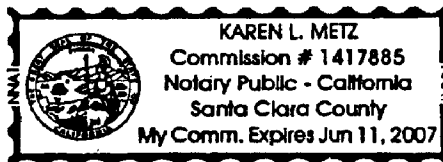
SS.

On this 23rd day of May, in the year 2006, before me, Karen L. Metz, Notary Public personally appeared Nghia Thuc Tu, personally known to me (or proved to me on the basis of satisfactory evidence) to be the person whose name is subscribed to the within instrument, and acknowledged to me that ~~he~~she executed the same in ~~his~~her authorized capacity(ies), and that by ~~his~~her signature on the instrument the person, or the entity upon behalf of which the person acted, executed the instrument.

WITNESS my hand and official seal.

Notary Signature

Karen L. Metz



ASSIGNMENT OF PATENT APPLICATION

Whereas I, an undersigned inventor, have invented certain new and useful improvements as set forth in the patent application entitled:

DIE ATTACH METHOD AND LEADFRAME STRUCTURE

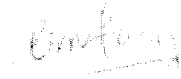
(Atty. Docket No. NSC1P349/P06556), (check one)

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☐ which is a U.S. provisional application. (Accompanying)

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- 3) Agree to execute all papers and documents and, entirely at the ASSIGNEE's expense, perform any acts which are reasonably necessary in connection with the prosecution of said application, as well as any derivative applications thereof, foreign applications based thereon, and/or the enforcement of patents resulting from such applications.
- 4) Agree that the terms, covenants and conditions of this assignment shall inure to the benefit of the ASSIGNEE, its successors, assigns and other legal representatives, and shall be binding upon the inventor, as well as the inventor's heirs, legal representatives and assigns.
- 5) Warrant and represent that I have not entered and will not enter into any assignment, contract, or understanding that conflicts with this assignment.
- 6) Authorize and request my attorney/agent to insert above the application No. in order to assist with recordal of this assignment.

Signed on the date indicated beside my signature.

- | | | |
|----|---|----------------------------|
| 1) | Signature: <u></u> | Date: <u>2nd Sept 2011</u> |
| | Typed Name: Lim Fong | |
| 2) | Signature: _____ | Date: _____ |
| | Typed Name: Chan Peng Yeen | |

ASSIGNMENT OF PATENT APPLICATION

Whereas I, an undersigned inventor, have invented certain new and useful improvements as set forth in the patent application entitled:

DIE ATTACH METHOD AND LEADFRAME STRUCTURE

(Atty. Docket No. NSC1P349/P06556), (check one)

- ☐ for which I have executed a U.S. patent application on even date herewith. (Accompanying)
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- 6) Authorize and request my attorney/agent to insert above the application No. in order to assist with recordal of this assignment.

Signed on the date indicated beside my signature.

- 1) Signature: _____ Date: _____
Typed Name: Lim Fong
- 2) Signature: _____ Date: 1.6.06
Typed Name: Chan Peng Yeen

If signed outside the United States of America, have two witnesses who also sign below:

- 1) Signature: _____ Date: _____
Printed Name: _____
- 2) Signature: _____ Date: _____

NSC1P349/P06556
Revised 06/01, Assign US or Foreign No Notary